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## INFORMATION DISCLOSURE STATEMENT

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APPLICANT(S): Hunt et al.

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## UNITED STATES PATENT DOCUMENTS

EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILE DATE
ET	AA	3,481,781	12/02/69	Kern et al.	11	11	
	AB	4,277,525	07/07/81	Nakayama et al.	11	11	
	AC	4,501,602	02/26/85	Miller et al.	11	11	
	AD	4,645,524	02/24/87	Bocko et al.	11	11	
	AE	5,043,002	08/27/91	Dobbins et al.	11	11	
	AF	5,079,069	01/07/92	Howard et al.	11	11	
	AG	5,152,819	10/06/92	Blackwell et al.	11	11	
	AH	5,154,744	10/12/92	Blackwell et al.	11	11	
	AI	5,155,655	10/13/92	Howard et al.	11	11	
	AJ	5,161,086	11/03/92	Howard et al.	11	11	
	AK	5,261,153	11/16/93	Lucas	11	11	
	AL	5,347,258	01/13/94	Howard et al.	11	11	
	AM	5,356,672	10/18/94	Schmitt, III et al.	11	11	
	AN	5,410,107	04/25/95	Schaper	11	11	
	AO	5,454,847	10/03/95	Jacoboni et al.	11	11	
	AP	5,466,892	11/14/95	Howard et al.	11	11	
	AQ	5,652,021	07/29/97	Hunt et al.	11	11	
ET	AR	5,670,262	09/97	Dalman	11	11	

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRAN YES/NO
W	BA	WO 96/33298	04/08/96	International	11	11	
W	BB	WO 96/38429	03/18/97	International	11	11	

## OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

ET	CA	G. Stauf et al., "Thin Film High K Dielectrics for Integrated Passive Devices", <i>The International Journal of Microcircuits and Electronic Packaging</i> , Vol. 20 n.2, 2 <sup>nd</sup> qtr., 1997.
W	CB	Hunt et al., "Chemical Vapor Deposition and Powder Formation Using Thermal Spray with Near Supercritical and Supercritical Fluid Solutions", U.S. Patent Appl. Serial No. 08/691,853, filed 08/02/96.

Examiner:

Date:

5/31/02